

BRCO7330HME

CMOS

300mA

30V

CMOS

30V

B 300mA 2% 'ñ À-Àl ¯đMđ•@‡` l Á ý 8'4 Đô v

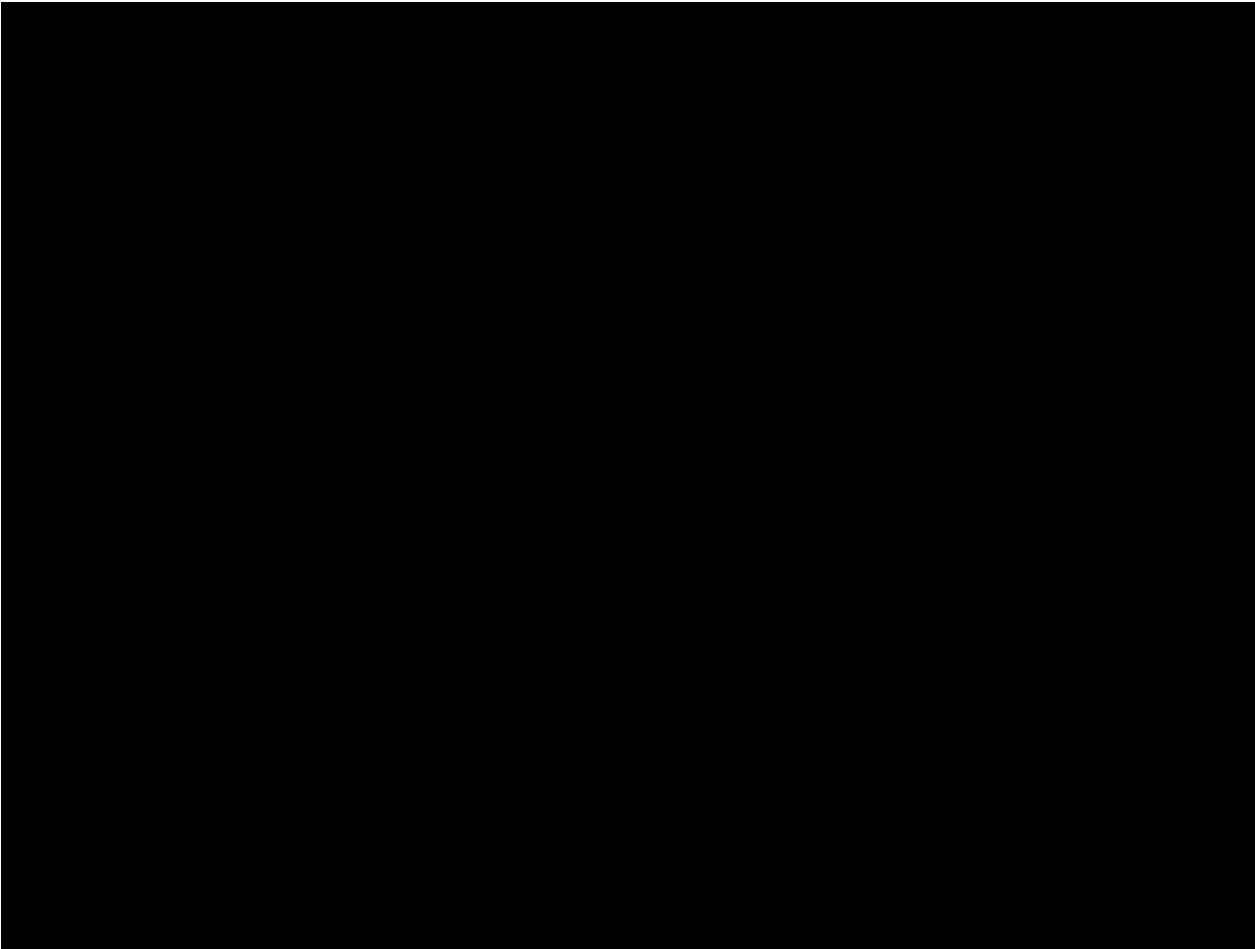
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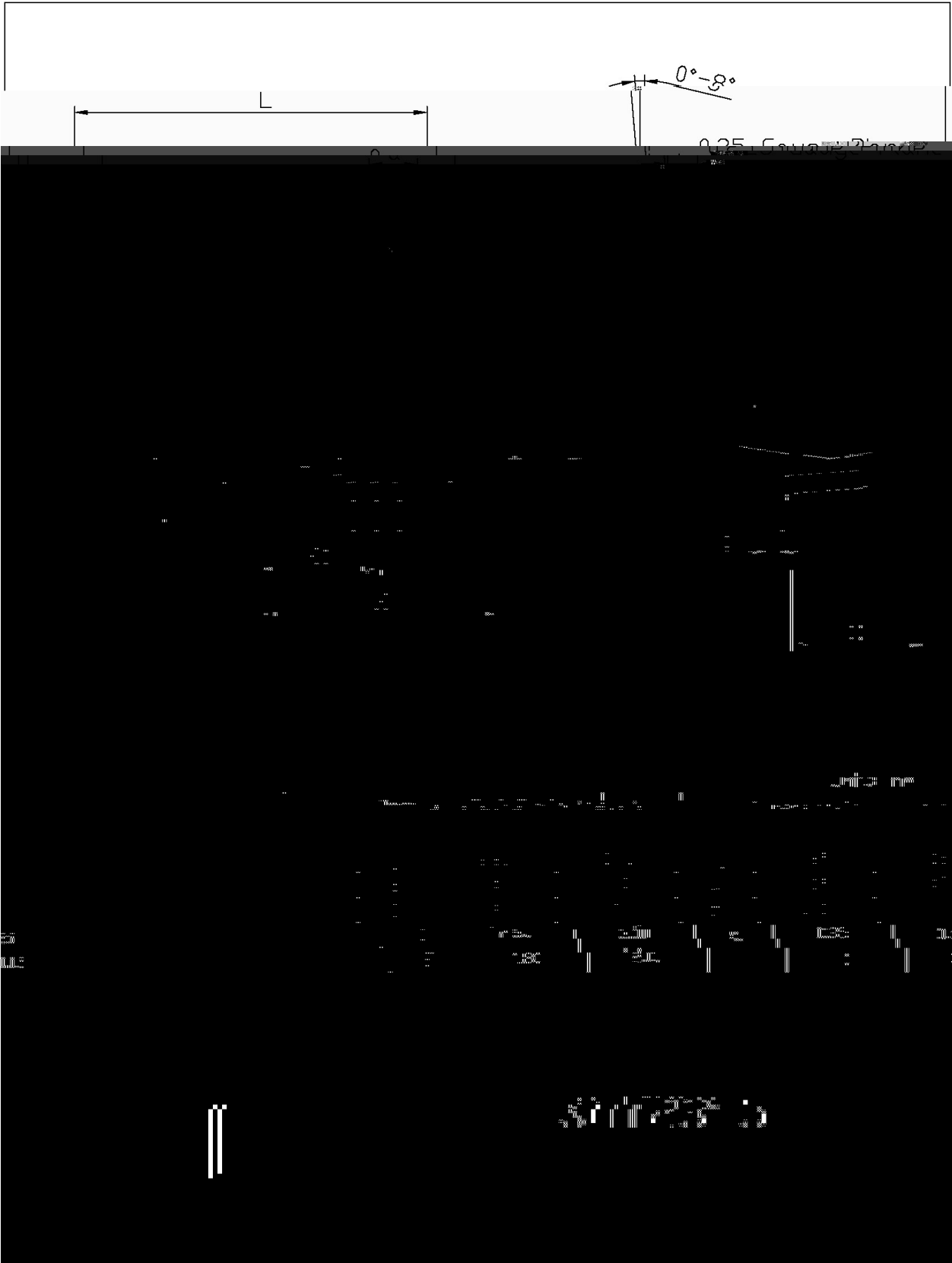
	V_{IN_MAX}	30	V
	V_{IN}	-0.3~30	V
CE	V_{CE}	$V_{IN}-0.3 \sim V_{IN}+0.3$	V
	I_{OUT}	0~500	mA
	P_D	0.3	W
	T_{stg}	-40 to +150	°C
	T_{OP}	-40 to +85	

	V_{IN}		2.5		24	V
	V_{OUT}	$I_{OUT}=10mA$	$V_{OUT} \times 0.98$		$V_{OUT} \times 1.02$	V
	I_{SS}	$I_{OUT}=0mA$	-	2.5	6	uA
	I_{ST}	CE=0V			0.2	uA
	I_{LIM}	-	500			mA
	V_{DROP}	$I_{OUT}=100mA$	-	200	-	mV
	I_{SHORT}			55		mA
	V_{CE_L}				0.4	V
	V_{CE_H}		1.5			V

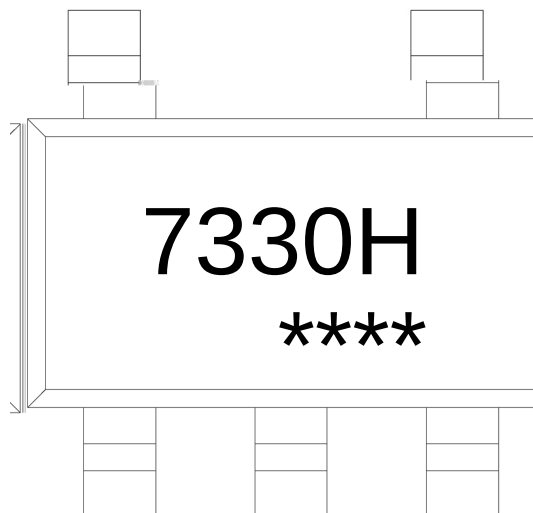
/ Functionl Block Diagram



/ Package Dimensions

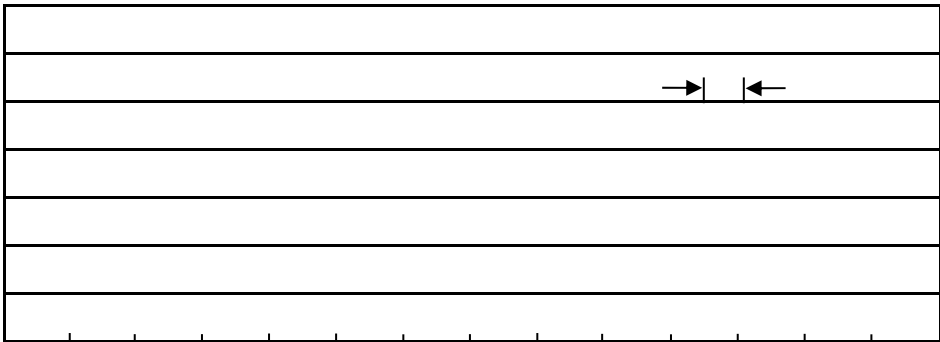


/ Marking Instructions



7330H

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.
- 2

245±5

5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.
- 3

2 10

/sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOT23-5/6	3,000	10	30,000	4	120,000	7 ×8	210×205×205	445×435×230

/ Notices

All information provided in this document is subject to legal disclaimers.